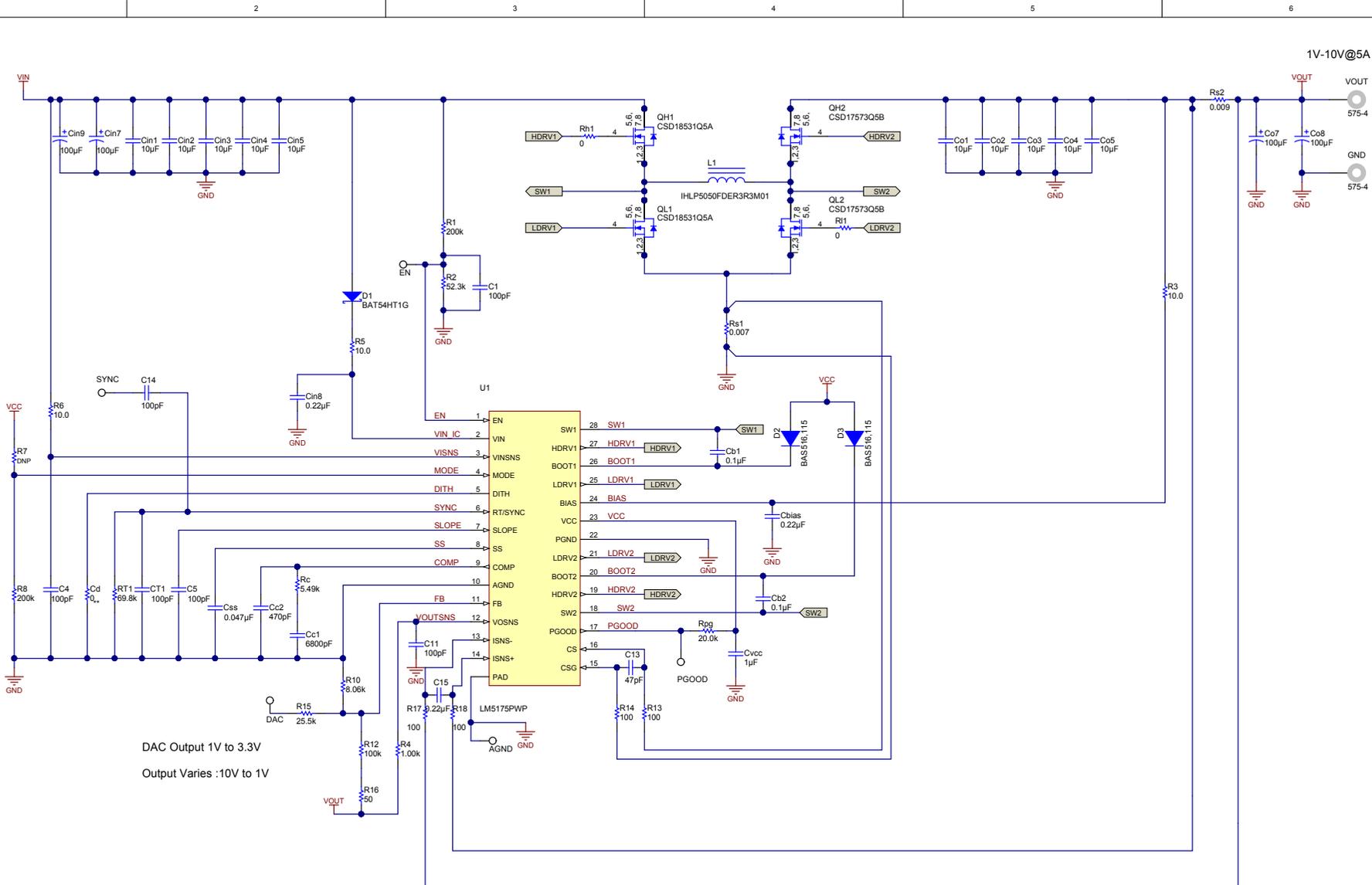


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Designed for: Public Release		Mod. Date: 7/14/2015	
Project Title: A13 Wireless Charger Front End - Automotive			
Number: PMP10709 R1 Rev: E1		Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet 1 of 1	
Drawn By:	File: PMP10709_Sch2_SchDoc	Size: B	http://www.ti.com
Engineer: Ambresh Tripathi	Contact: http://www.ti.com/support	© Texas Instruments 2015	



DAC Output 1V to 3.3V
Output Varies :10V to 1V

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Number: PMP10709 R1 [Rev: E1]	Designed for: Public Release	Mod. Date: 6/23/2015
SVN Rev: Not in version control	Project Title: A13 Wireless Charger Front End - Automotive	Sheet Title:
Drawn By:	Assembly Variant: [No Variations]	Sheet 1 of 1
Engineer: Ambresh Tripathi	File: PMP10609_Sch1_SchDoc	Size: B
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PCB Number: PMP10709 R1_B
PCB Rev: E1

PCB
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PCB
LOGO
Pb-Free Symbol

Label Table	
Variant	Label Text
001	LMS17SEVM-HD

LBL1
PCB Label
PMP10709 REV1

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Designed for: Public Release	Mod. Date: 6/23/2015	
Project Title: A13 Wireless Charger Front End - Automotive		
Number: PMP10709 R1 Rev: E1	Sheet Title: LMS17SEVM-HD HARDWARE	Sheet: 1 of 2
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Size: B
Drawn By: Alan Cuperus	File: HW_SchDoc	http://www.ti.com
Engineer: Ambresh Tripathi	Contact: http://www.ti.com/support	© Texas Instruments 2015

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